

IN THE  
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Xiang Dai et al.

Application No.: 10/612,663

Filing Date: July 2, 2003

Title: SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE HAVING A SOLDER COLUMN ARRAY

Confirmation No.: 5441

Examiner: James M. Mitchell

Group Art Unit: 2813

Mail Stop AF  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- (X) Response/Amendment ( ) Petition to extend time to respond  
( ) New fee as calculated below ( ) Supplemental Declaration  
(X) No additional fee  
(X) Other: Return postcard (fee \$ )

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	15	MINUS	20	= 0	X \$50	\$ 0
INDEP. CLAIMS	4	MINUS	4	= 0	X \$200	\$ 0
[ ] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$360	\$ 0
EXTENSION FEE	1ST MONTH \$120.00	2ND MONTH \$450.00	3RD MONTH \$1020.00	4TH MONTH \$1590.00		\$ 0
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16 through 1.21 inclusive, and any other sections in Title 37 of the Code of Federal Regulations that may regulate fees. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

Xiang Dai et al.

By

Paul S. Grunzweig

Attorney/Agent for Applicant(s)  
Reg. No. 37,143

Date: April 14, 2005

Date of Deposit: April 14, 2005

Typed Name: Paul S. Grunzweig

Signature: Paul S. Grunzweig



**EXPEDITED PROCEDURE**  
**Examining Group Number 2800**

**THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Xiang Dai et al.	Examiner:	James M. Mitchell
Serial No.:	10/612,663	Group Art Unit:	2813
Filed:	July 2, 2003	Docket No.:	200308566-1
Title:	SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE HAVING A SOLDER COLUMN ARRAY		

---

**AMENDMENT AND RESPONSE UNDER 37 C.F.R. 1.116**

**Mail Stop AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This Amendment and Response is in reply to the Final Office Action mailed February 17, 2005. Please amend the above-identified patent application as follows: